## **Power MOSFET** 40 V, 0.7 mΩ, 378 A, Single N–Channel

#### Features

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- NVMFS5C404NWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant



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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
40 V	0.7 mΩ @ 10 V	378 A

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted) Parameter Symbol Value Unit Drain-to-Source Voltage VDSS 40 V v Gate-to-Source Voltage V<sub>GS</sub> ±20 $I_{\mathsf{D}}$ Continuous Drain $T_{\rm C} = 25^{\circ}{\rm C}$ 378 A Current R<sub>0JC</sub> $T_C = 100^{\circ}C$ 267 (Notes 1, 3) Steady State Power Dissipation $P_D$ W $T_C = 25^{\circ}C$ 200 $R_{\theta JC}$ (Note 1) $T_{\rm C} = 100^{\circ}{\rm C}$ 100 Continuous Drain $T_A = 25^{\circ}C$ 53 A $I_D$ Current $R_{\theta JA}$ (Notes 1, 2, 3) $T_A = 100^{\circ}C$ 37 Steady State Power Dissipation $T_{\Delta} = 25^{\circ}C$ PD 3.9 W R<sub>θJA</sub> (Notes 1 & 2) 1.9 $T_A = 100^{\circ}C$ **Pulsed Drain Current** $T_A = 25^{\circ}C$ , $t_p = 10 \ \mu s$ 900 $I_{DM}$ A °C **Operating Junction and Storage Temperature** -55 to T<sub>J</sub>, T<sub>sta</sub> + 175 Source Current (Body Diode) ls 191 A $\mathsf{E}_{\mathsf{AS}}$ Single Pulse Drain-to-Source Avalanche 907 mJ Energy $(I_{L(pk)} = 38 \text{ A})$ Lead Temperature for Soldering Purposes ΤL 260 °C (1/8'' from case for 10 s)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

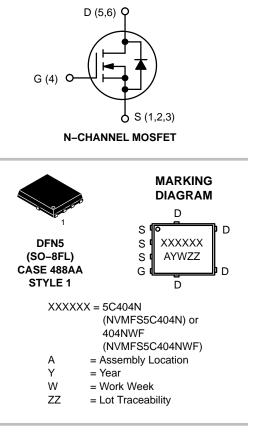
#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{ extsf{ heta}JC}$	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\thetaJA}$	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
Maximum current for pulses as long as 1 second is higher but is do

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



#### ORDERING INFORMATION

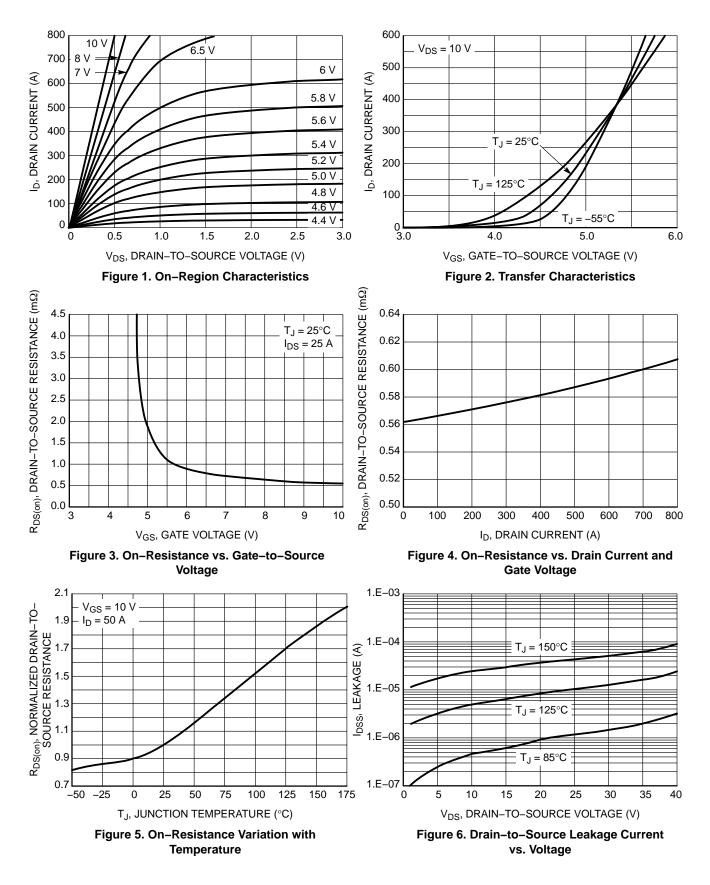
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise specified)

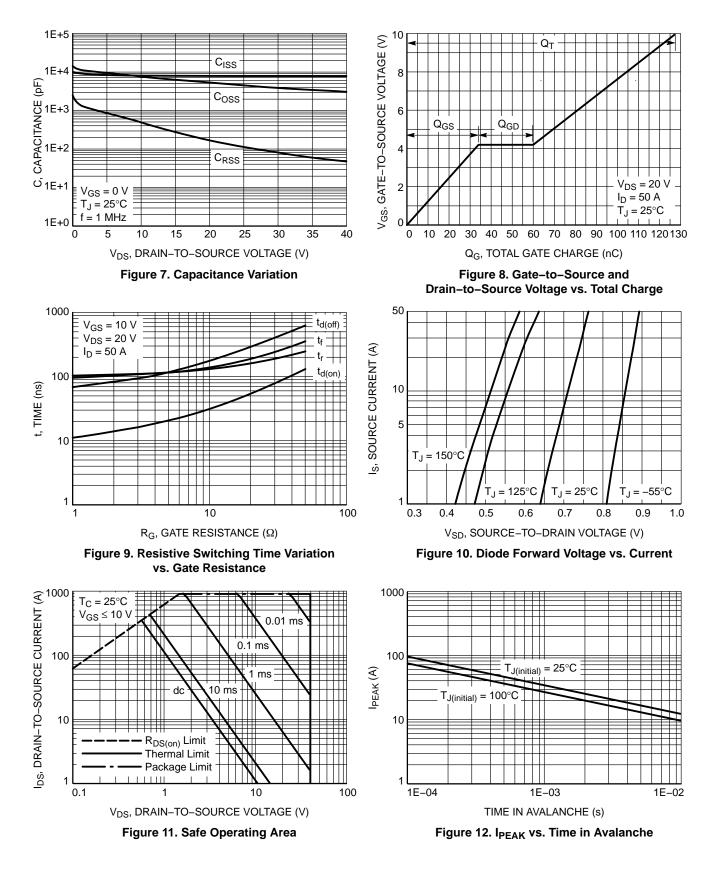
Parameter	Symbol	Test Condition		Min	Тур	Мах	Unit
OFF CHARACTERISTICS					•		•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 $\mu$ A		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>				19.7		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 40 V	T <sub>J</sub> = 25 °C			10	
	$V_{DS} = 40 V \qquad T_{J} = 125$	T <sub>J</sub> = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V				100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D$	= 250 μA	2.0		4.0	V
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-6.2		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		0.57	0.7	mΩ
Forward Transconductance	9fs	V <sub>DS</sub> =15 V, I <sub>D</sub>	) = 50 A		210		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}, V_{DS} = 25 \text{ V}$ $V_{GS} = 10 \text{ V}, V_{DS} = 20 \text{ V}; \text{ I}_{D} = 50 \text{ A}$			8400		pF
Output Capacitance	C <sub>OSS</sub>				4600		
Reverse Transfer Capacitance	C <sub>RSS</sub>				120		
Total Gate Charge	Q <sub>G(TOT)</sub>				128		
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 50 A			22		
Gate-to-Source Charge	Q <sub>GS</sub>				35		
Gate-to-Drain Charge	Q <sub>GD</sub>				26		
Plateau Voltage	V <sub>GP</sub>				4.3		V
SWITCHING CHARACTERISTICS (Note 5	5)				•		•
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 20 V, I <sub>D</sub> = 50 A, R <sub>G</sub> = 2.5 Ω			16		ns
Rise Time	t <sub>r</sub>				113		
Turn-Off Delay Time	t <sub>d(OFF)</sub>				77		
Fall Time	t <sub>f</sub>				109		
DRAIN-SOURCE DIODE CHARACTERIS	TICS					•	
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.76	1.2	
I <sub>S</sub> =	$I_{\rm S} = 50 \rm{A}$	T <sub>J</sub> = 125°C		0.63		V	
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dIS/dt = 100 A/μs, I <sub>S</sub> = 50 A			96		ns
Charge Time	ta				49		
Discharge Time	t <sub>b</sub>				47		
Reverse Recovery Charge	Q <sub>RR</sub>				189		nC

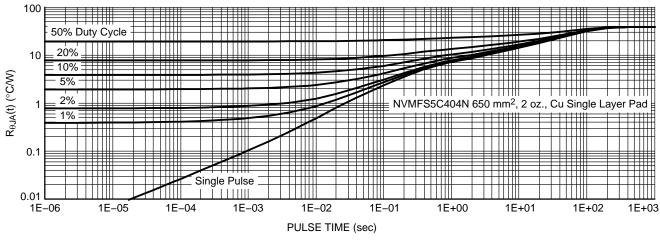
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width  $\leq 300 \,\mu$ s, duty cycle  $\leq 2\%$ . 5. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**





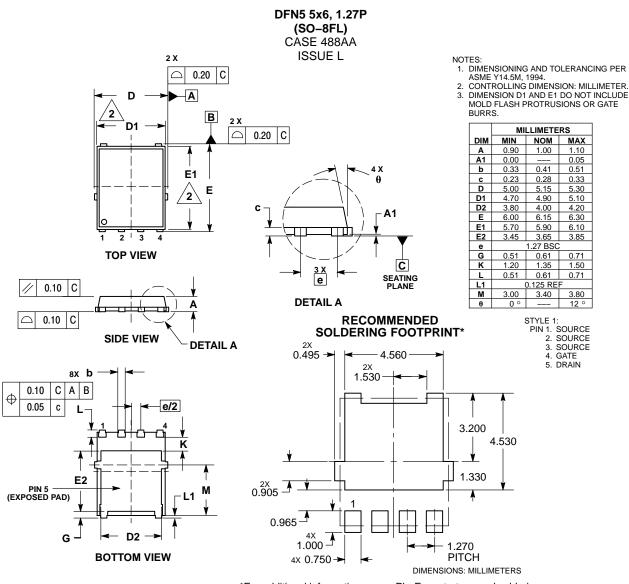


#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5C404NT1G	5C404N	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5C404NWFT1G	404NWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C404NT3G	5C404N	DFN5 (Pb–Free)	5000 / Tape & Reel
NVMFS5C404NWFT3G	404NWF	DFN5 (Pb–Free, Wettable Flanks)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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